

26–33 GHz Surface Mount Single Balanced Down Converter Mixer



AM028S1-A2
Patent Pending

Features

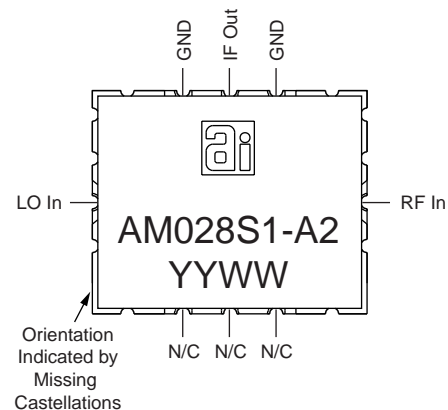
- Surface Mount Package
- Low Conversion Loss, 6 dB
- Low LO Power Requirement, 8 dBm
- Wide IF Bandwidth, 0–6 GHz
- No DC Bias Required
- 100% RF Testing for Conversion Loss

Description

The AM028S1-A2 is a broadband millimeterwave mixer in a rugged surface mount package that is compatible with high volume solder installation. The single balanced down converter mixer is designed for use in millimeterwave communication and sensor systems as a frequency conversion stage in the receiver chain when wide dynamic range and high linearity are required. The robust ceramic surface mount package provides excellent electrical performance and a high degree of environmental protection for long-term reliability. All mixers are screened at the operating frequencies prior to shipment for guaranteed performance. Mixer is targeted for high volume millimeterwave applications such as point-to-point and point-to-multipoint wireless communications systems.



Pin Out

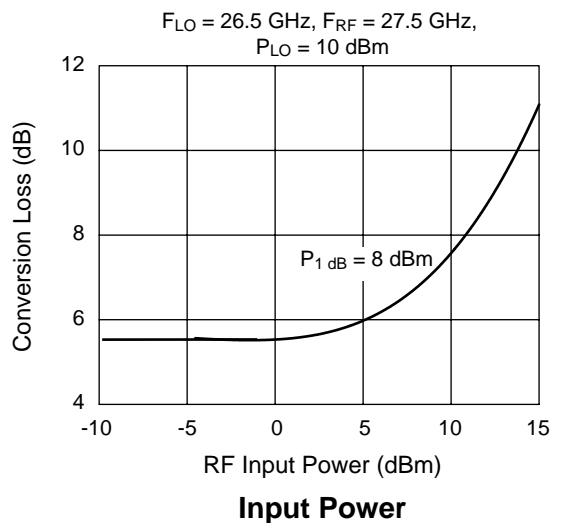
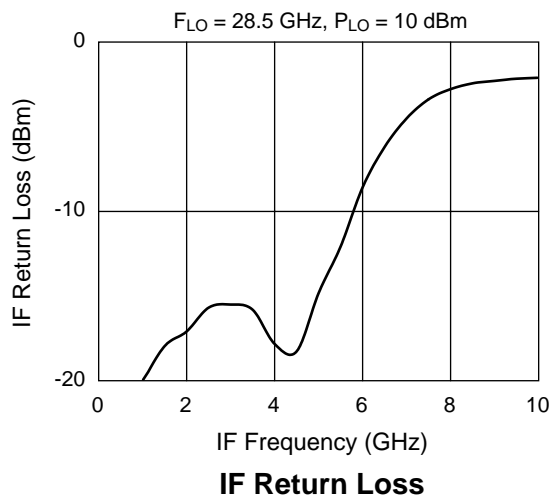
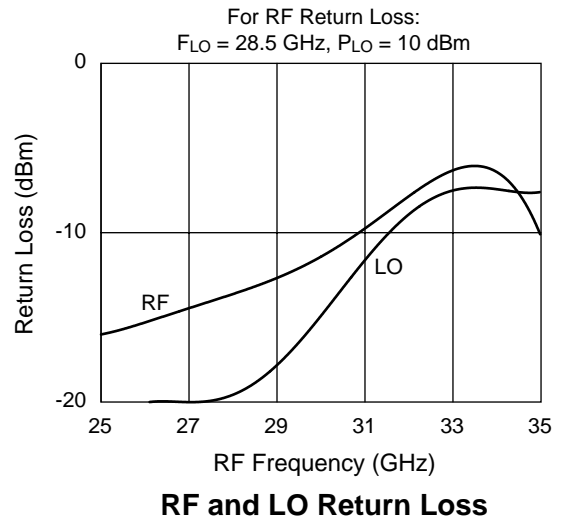
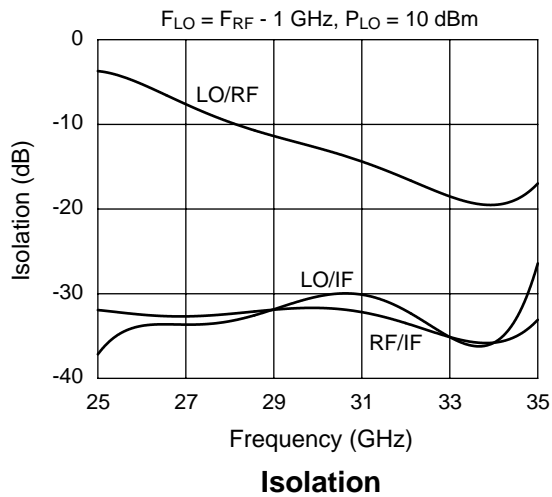
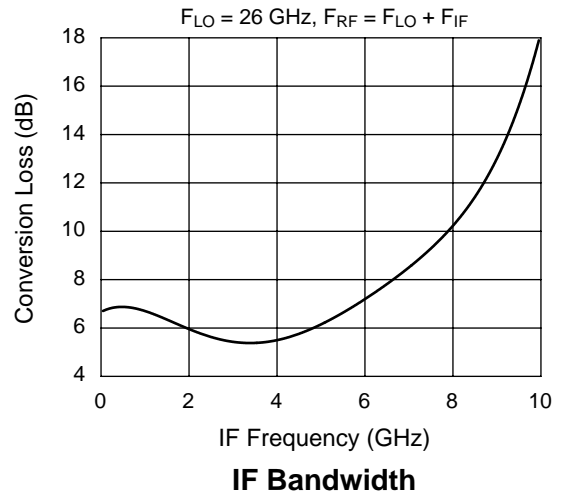
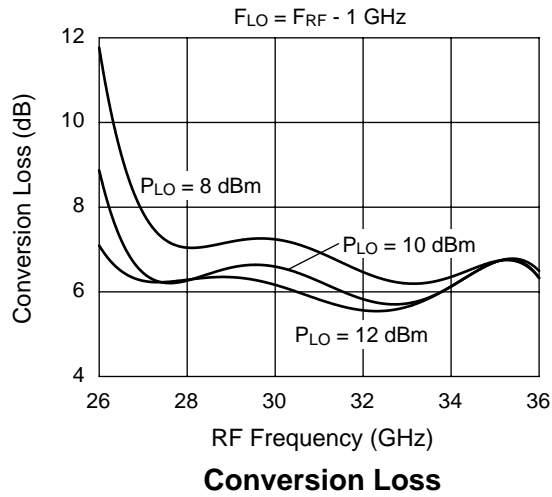


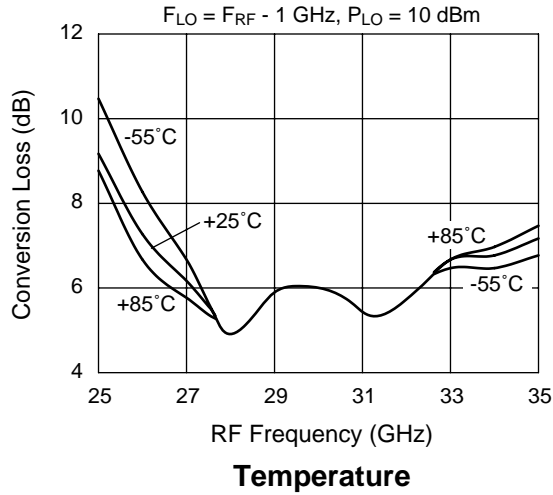
Electrical Specifications at 25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit
RF and LO Frequency Range ²	F_{RF}, F_{LO}		26–33		GHz
IF Frequency Range ²	F_{IF}		0–6		GHz
LO Power Level ²	P_{LO}		8–18		dBm
Conversion Loss ¹	L_C		6	8	dB
RF, LO and IF Return Loss ²	RL		10		dB
LO to RF Isolation ²	ISO_{LO-RF}		10		dB
LO to IF Isolation ²	ISO_{LO-IF}		30		dB
RF to IF Isolation ²	ISO_{RF-IF}		30		dB
RF Input 1 dB Compression Point ²	P_1 dB		8		dBm

1. Conversion loss is measured at $F_{RF} = 28$ GHz, $F_{LO} = 26$ GHz, $P_{LO} = 10$ dBm on 100% of parts.
2. Not measured on a 100% basis.

Typical Performance Data

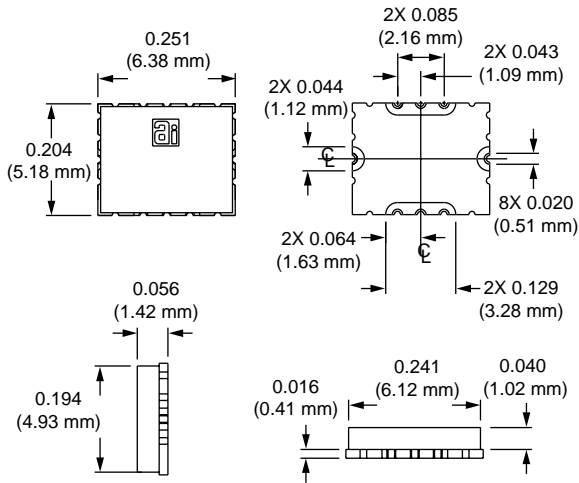




Absolute Maximum Ratings

Characteristic	Value
Operating Temperature (T_C)	-55°C to +85°C
Storage Temperature (T_{ST})	-65°C to +125°C
Total Input Power (RF + LO)	+20 dBm

-A2



“Alpha Two” Surface Mount Package Handling and Mounting

Millimeterwave components require careful mounting design to maintain optimal performance. The Alpha Two surface mount package (patent pending) provides a rugged and repeatable electrical connection using standard solder techniques.

Handling

The Alpha Two surface mount package is very rugged. However, due to ceramic’s brittle nature, one should exercise care when handling with metal tools. Do not apply heavy pressure to the lid. Vacuum tools may be used to pick and place this part.

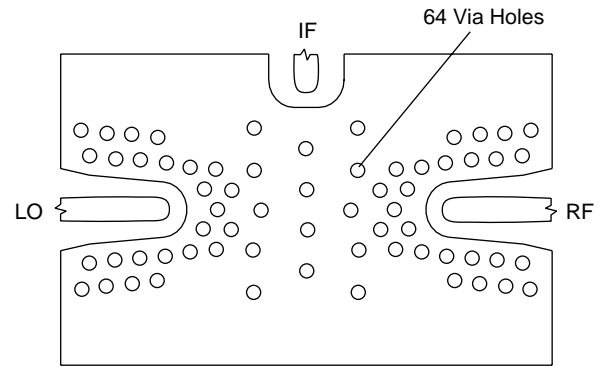
Only personnel trained in both ESD precautions and handling precautions should be allowed to handle these packages.

Package Construction

The Alpha Two surface mount package consists of a base and a lid. The package base is ceramic with filled vias and plated castellations. The package lid is unplated alumina. The lid seal is epoxy.

Mounting Design

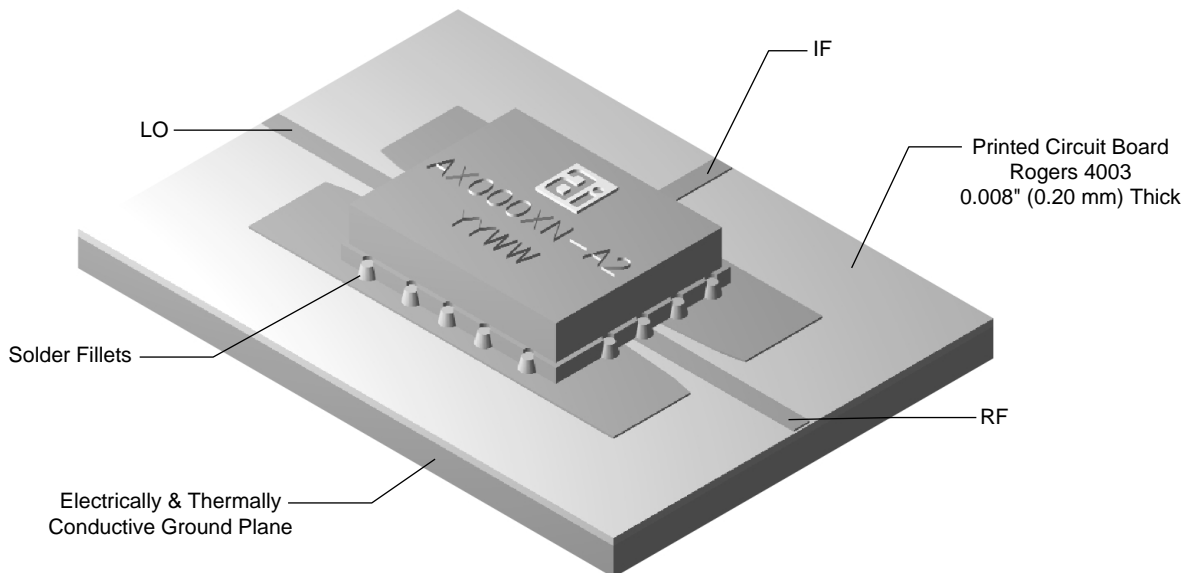
The Alpha Two surface mount package is installed on top of a printed circuit board on a specially designed footprint. Mounting footprint geometry will be supplied by Alpha Industries in electronic formats or paper drawing.



**Footprint Geometry for Alpha Two
Surface Mount Package (for AM028S1-A2 mixer only)**

Mounting the Package

The Alpha Two surface mount package is compatible with high-volume surface mount installation using solder. RF, LO and IF connections are accomplished with metallized edge castellations that hold solder fillets. Ground connections are accomplished by both metallized edge castellations and filled vias to the bottom of the package. Care should be taken to ensure that there are no voids or gaps in the solder so that good RF, LO, IF, and ground contact is maintained.



Alpha Two Surface Mount Package Installation